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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc66-04-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

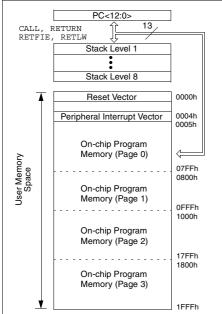
Pin Name	DIP Pin#	SOIC Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	16	16	I	ST/CMOS(1)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	0	_	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0	17	17	I/O	TTL	
RA1	18	18	I/O	TTL	
RA2	1	1	I/O	TTL	
RA3	2	2	I/O	TTL	
RA4/T0CKI	3	3	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software pro- grammed for internal weak pull-up on all inputs.
RB0/INT	6	6	I/O	TTL/ST ⁽²⁾	RB0 can also be the external interrupt pin.
RB1	7	7	I/O	TTL	
RB2	8	8	I/O	TTL	
RB3	9	9	I/O	TTL	
RB4	10	10	I/O	TTL	Interrupt on change pin.
RB5	11	11	I/O	TTL	Interrupt on change pin.
RB6	12	12	I/O	TTL/ST ⁽³⁾	Interrupt on change pin. Serial programming clock.
RB7	13	13	I/O	TTL/ST ⁽³⁾	Interrupt on change pin. Serial programming data.
Vss	5	5	Р	-	Ground reference for logic and I/O pins.
Vdd	14	14	Р	_	Positive supply for logic and I/O pins.
Legend: I = input	0 = ou — = N	utput lot used) = input/outpu L = TTL input	

PIC16C61 PINOUT DESCRIPTION TABLE 3-1:

 Note
 1:
 This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.
 2:
 This buffer is a Schmitt Trigger input when configured as the external interrupt.
 Configured as the external interrup

3: This buffer is a Schmitt Trigger input when used in serial programming mode.

FIGURE 4-4: PIC16C66/67 PROGRAM MEMORY MAP AND STACK



4.2 Data Memory Organization

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67 The data memory is partitioned into multiple banks

which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1:RP0 (STATUS<6:5>)

- = 00 \rightarrow Bank0
- = 01 \rightarrow Bank1
- = 10 \rightarrow Bank2
- = 11 \rightarrow Bank3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some "high use" special function registers from one bank may be mirrored in another bank for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTERS

These registers are accessed either directly or indirectly through the File Select Register (FSR) (Section 4.5). For the PIC16C61, general purpose register locations 8Ch-AFh of Bank 1 are not physically implemented. These locations are mapped into 0Ch-2Fh of Bank 0.

FIGURE 4-5: PIC16C61 REGISTER FILE MAP

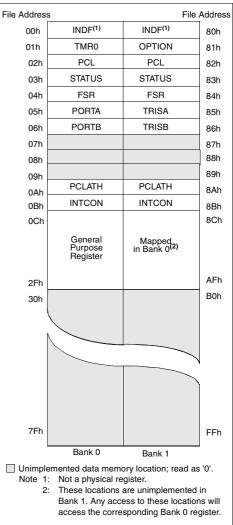


FIGURE 4-8: PIC16C66/67 DATA MEMORY MAP

ndirect addr.(*)	00h	Indirect addr.(*)	80h	Indirect addr.(*)	100h	Indirect addr.(*)	180
TMR0	01h	OPTION	81h	TMR0	101h	OPTION	181
PCL	02h	PCL	82h	PCL	102h	PCL	182
STATUS	03h	STATUS	83h	STATUS	103h	STATUS	183
FSR	04h	FSR	84h	FSR	104h	FSR	184
PORTA	05h	TRISA	85h		105h	1011	185
PORTB	06h	TRISB	86h	PORTB	106h	TRISB	186
PORTC	07h	TRISC	87h		107h		187
PORTD (1)	08h	TRISD (1)	88h		108h		188
PORTE (1)	09h	TRISE (1)	89h		109h		189
PCLATH	0Ah	PCLATH	8Ah	PCLATH	10Ah	PCLATH	184
INTCON	0Bh	INTCON	8Bh	INTCON	10Bh	INTCON	18E
PIR1	0Ch	PIE1	8Ch		10Ch		180
PIR2	0Dh	PIE2	8Dh		10Dh		180
TMR1L	0Eh	PCON	8Eh		10Eh		18
TMR1H	0Fh	TOON	8Fh		10Fh		18F
T1CON	10h		90h		110h		190
TMR2	11h		91h		111h		191
T2CON	12h	PR2	92h		112h		192
SSPBUF	13h	SSPADD	93h		113h		193
SSPCON	14h	SSPSTAT	94h		114h		194
CCPR1L	15h	30F 5TAT	95h		115h		195
CCPR1H	16h		96h		116h		196
CCP1CON	17h		97h	General	117h	General	197
RCSTA	18h	TXSTA	98h	Purpose	118h	Purpose	198
TXREG	19h	SPBRG	99h	Register 16 Bytes	119h	Register 16 Bytes	199
RCREG	1Ah	SEDITO	9Ah	TO Bytes	11Ah	TO Dytes	194
CCPR2L	1Bh		9Bh		11Bh		19E
CCPR2H	1Ch		9Ch		11Ch		190
CCP2CON	1Dh		9Dh		11Dh		190
0012001	1Eh		9Eh		11Eh		19E
	1Fh		9Fh		11Fh		19F
	20h		-		120h		-
	2011		A0h		12011		1A0
General Purpose Register 96 Bytes		General Purpose Register 80 Bytes	EFh	General Purpose Register 80 Bytes	16Fh	General Purpose Register 80 Bytes	1EF
	7Fh	accesses 70h-7Fh in Bank 0	F0h FFh	accesses 70h-7Fh in Bank 0	170h 17Fh	accesses 70h-7Fh in Bank 0	1FC
Bank 0		Bank 1		Bank 2		Bank 3	
Not a physical	register.	mory locations, read					
		ytes of data memo		nks 1, 2, and 3 are			

8.1 <u>Timer1 Operation in Timer Mode</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer mode is selected by clearing bit TMR1CS (T1CON<1>). In this mode, the input clock to the timer is Fosc/4. The synchronize control bit $\overline{T1SYNC}$ (T1CON<2>) has no effect since the internal clock is always in sync.

8.2 <u>Timer1 Operation in Synchronized</u> <u>Counter Mode</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Counter mode is selected by setting bit TMR1CS. In this mode the timer increments on every rising edge of clock input on T1OSI when enable bit T1OSCEN is set or pin with T1CKI when bit T1OSCEN is cleared.

Note:	The T1OSI function is multiplexed to differ-
	ent pins, depending on the device. See the
	pinout descriptions to see which pin has
	the T1OSI function.

If T1SYNC is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple counter.

In this configuration, during SLEEP mode, Timer1 will not increment even if an external clock is present, since the synchronization circuit is shut off. The prescaler, however, will continue to increment.

8.2.1 EXTERNAL CLOCK INPUT TIMING FOR SYNCHRONIZED COUNTER MODE

When an external clock input is used for Timer1 in synchronized counter mode, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of TMR1 after synchronization.

When the prescaler is 1:1, the external clock input is the same as the prescaler output. The synchronization of T1CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, it is necessary for T1CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to appropriate electrical specification section, parameters 45, 46, and 47.

When a prescaler other than 1:1 is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. In order for the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T1CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T1CKI high and low time is that they do not violate the minimum pulse width requirements of 10 ns). Refer to applicable electrical specification section, parameters 40, 42, 45, 46, and 47.

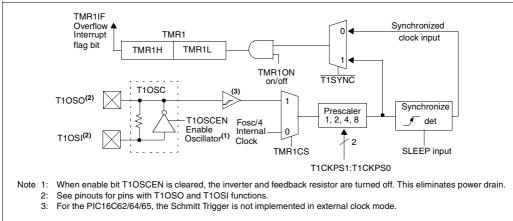


FIGURE 8-2: TIMER1 BLOCK DIAGRAM

10.3 PWM Mode

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

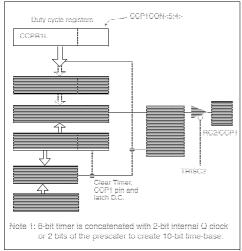
In Pulse Width Modulation (PWM) mode, the CCP1 pin produces up to a 10-bit resolution PWM output. Since the CCP1 pin is multiplexed with the PORTC data latch, the TRISC<2> bit must be cleared to make the CCP1 pin an output.

Note: Clearing the CCP1CON register will force the CCP1 PWM output latch to the default low level. This is not the PORTC I/O data latch.

Figure 10-4 shows a simplified block diagram of the CCP module in PWM mode.

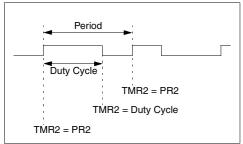
For a step by step procedure on how to set up the CCP module for PWM operation, see Section 10.3.3.

FIGURE 10-4: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 10-5) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/period).

FIGURE 10-5: PWM OUTPUT



10.3.1 PWM PERIOD

The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

PWM period = [(PR2) + 1] • 4 • TOSC • (TMR2 prescale value)

PWM frequency is defined as 1 / [PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The PWM duty cycle is latched from CCPR1L into CCPR1H
- The CCP1 pin is set (exception: if PWM duty cycle = 0%, the CCP1 pin will not be set)

Note:	The Timer2 postscaler (see Section 9.1) is
	not used in the determination of the PWM
	frequency. The postscaler could be used to
	have a servo update rate at a different fre-
	quency than the PWM output.

10.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available: the CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR1L:CCP1CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

PWM duty cycle = (CCPR1L:CCP1CON<5:4>) • Tosc • (TMR2 prescale value)

CCPR1L and CCP1CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR1H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

When the CCPR1H and 2-bit latch match TMR2 concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP1 pin is cleared.

Maximum PWM resolution (bits) for a given PWM frequency:

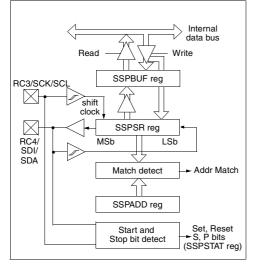
$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \quad \text{bits}$$

Note: If the PWM duty cycle value is longer than the PWM period the CCP1 pin will not be forced to the low level.

11.5 <u>SSP I²C Operation</u>

The SSP module in I^2C mode fully implements all slave functions, except general call support, and provides interrupts on start and stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing. Two pins are used for data transfer. These are the RC3/SCK/SCL pin, which is the clock (SCL), and the RC4/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISC<4:3> bits. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSP-CON<5>).

FIGURE 11-24: SSP BLOCK DIAGRAM (I²C MODE)



The SSP module has five registers for I^2C operation. These are the:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I^2C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I^2C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with start and stop bit interrupts enabled
- I²C Slave mode (10-bit address), with start and stop bit interrupts enabled
- I²C Firmware controlled Master Mode, slave is idle

Selection of any I^2C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits.

The SSPSTAT register gives the status of the data transfer. This information includes detection of a START or STOP bit, specifies if the received byte was data or address if the next byte is the completion of 10-bit address, and if this will be a read or write data transfer. The SSPSTAT register is read only.

The SSPBUF is the register to which transfer data is written to or read from. The SSPSR register shifts the data in or out of the device. In receive operations, the SSPBUF and SSPSR create a doubled buffered receiver. This allows reception of the next byte to begin before reading the last byte of received data. When the complete byte is received, it is transferred to the SSPBUF register and flag bit SSPIF is set. If another complete byte is received before the SSPBUF register is read, a receiver overflow has occurred and bit SSPOV (SSPCON<6>) is set and the byte in the SSPSR is lost.

The SSPADD register holds the slave address. In 10-bit mode, the user first needs to write the high byte of the address (1111 0 A9 A8 0). Following the high byte address match, the low byte of the address needs to be loaded (A7:A0).

12.1 USART Baud Rate Generator (BRG)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

Fosc = 16 MHz Desired Baud Rate = 9600 BRGH = 0 SYNC = 0

EXAMPLE 12-1: CALCULATING BAUD RATE ERROR

Desired Baud rate = Fosc / (64 (X + 1))

9600 = 16000000 / (64 (X + 1))

 $X = \lfloor 25.042 \rfloor = 25$

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

- Error = <u>(Calculated Baud Rate Desired Baud Rate)</u> Desired Baud Rate
 - = (9615 9600) / 9600

= 0.16%

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Note:	For the PIC16C63/R63/65/65A/R65 the
	asynchronous high speed mode
	(BRGH = 1) may experience a high rate of
	receive errors. It is recommended that
	BRGH = 0. If you desire a higher baud rate
	than BRGH = 0 can support, refer to the
	device errata for additional information or
	use the PIC16C66/67.

Writing a new value to the SPBRG register, causes the BRG timer to be reset (or cleared), this ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

TABLE 12-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = Fosc/(64(X+1))	Baud Rate = Fosc/(16(X+1))
1	(Synchronous) Baud Rate = Fosc/(4(X+1))	N/A

X = value in SPBRG (0 to 255)

TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets	
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010	
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x	
99h	SPBRG Baud Rate Generator Register										0000 0000	

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

Steps to follow when setting up an Asynchronous Transmission:

- 1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, then set bit BRGH. (Section 12.1).
- 2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
- 3. If interrupts are desired, then set enable bit TXIE.
- 4. If 9-bit transmission is desired, then set transmit bit TX9.

- 5. Enable the transmission by setting bit TXEN, which will also set bit TXIF.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Load data to the TXREG register (starts transmission).

FIGURE 12-8: ASYNCHRONOUS MASTER TRANSMISSION

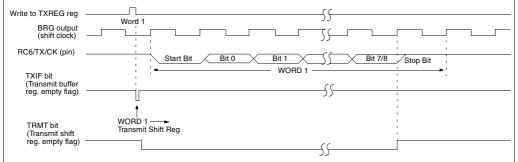


FIGURE 12-9: ASYNCHRONOUS MASTER TRANSMISSION (BACK TO BACK)

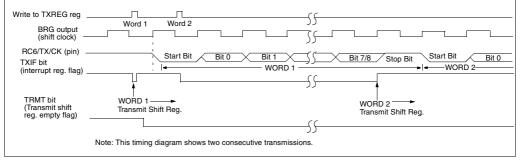


TABLE 12-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Tra	ansmit R	egister						0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate	Baud Rate Generator Register								0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Transmission.

Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

12.3 USART Synchronous Master Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Synchronous Master mode the data is transmitted in a half-duplex manner i.e., transmission and reception do not occur at the same time. When transmitting data the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition enable bit SPEN (RCSTA<7>) is set in order to configure the RC6 and RC7 I/O pins to CK (clock) and DT (data) lines respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

12.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR register is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcycle), the TXREG register is empty and interrupt flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the status of enable bit TXIE and cannot be cleared in software. It will clear only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR register is not mapped in data memory so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 12-12). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN (Figure 12-13). This is advantageous when slow baud rates are selected, since the BRG is kept in reset when bits TXEN. CREN, and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG register. Back-to-back transfers are possible.

Clearing enable bit TXEN, during a transmission, will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If, during a transmission, either bit CREN or bit SREN is set the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic however, is not reset although it is disconnected from the pins. In order to reset the transmitter, the user has to clear enable bit TXEN. If enable bit SREN is set (to interrupt an on going transmission and receive a single word), then after the single word is received, enable bit SREN will be cleared, and the serial port will revert back to transmitting since enable bit TXEN is still set. The DT line will immediately switch from hi-impedance receive mode to transmit and start driving. To avoid this, enable bit TXEN should be cleared.

In order to select 9-bit transmission, bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR register was empty and the TXREG register was written before writing the "new" TX9D, the "present" value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

- 1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
- 2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
- 3. If interrupts are desired, then set enable bit $\ensuremath{\mathsf{TXIE}}$.
- 4. If 9-bit transmission is desired, then set bit TX9.
- 5. Enable the transmission by setting enable bit TXEN.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Start transmission by loading data to the TXREG register.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

17.2 DC Characteristics: PIC16LC62/64-04 (Commercial, Industrial)

$\begin{tabular}{lllllllllllllllllllllllllllllllllll$								
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions	
D001	Supply Voltage	Vdd	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)	
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V		
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details	
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details	
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)	
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C	
D021	(Note 3, 5)		-	0.9	13.5	μA	VDD = $3.0V$, WDT disabled, $0^{\circ}C$ to $+70^{\circ}C$	
D021A			-	0.9	18	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

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FIGURE 17-3: CLKOUT AND I/O TIMING

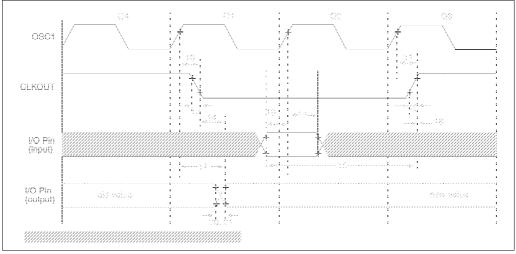


TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameters	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		-	75	200	ns	Note 1
11*	TosH2ckH	OSC1 [↑] to CLKOUT [↑]		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		—		0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT	↑	Tosc + 200		_	ns	Note 1
16*	TckH2ioI	Port in hold after CLKOUT 1	0		_	ns	Note 1	
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out	OSC1↑ (Q1 cycle) to Port out valid			150	ns	
18*	TosH2iol	OSC1 [↑] (Q2 cycle) to Port	PIC16 C 62/64	100		_	ns	
		input invalid (I/O in hold time)	PIC16LC62/64	200		_	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0		—	ns	
20*	TioR	Port output rise time	PIC16 C 62/64	—	10	40	ns	
			PIC16LC62/64	—		80	ns	
21*	TioF	Port output fall time	Port output fall time PIC16 C 62/64		10	40	ns	
		PIC16 LC 62/64		—		80	ns	
22††*	Tinp	INT pin high or low time	•	Тсү	_	—	ns	
23††*	Trbp	RB7:RB4 change INT high or	low time	Тсү	_	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

these parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



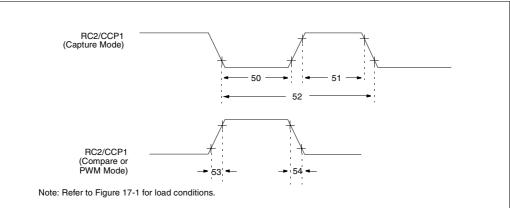


TABLE 17-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions		
50*	TccL	CCP1	No Prescaler		0.5Tcy + 20	—	_	ns	
		input low time	With Prescaler	PIC16 C 62/64	10	—	—	ns	
				PIC16LC62/64	20	_	_	ns	
51*	TccH	CCP1	No Prescaler		0.5Tcy + 20	_	_	ns	
	input high time	With Prescaler	PIC16 C 62/64	10	_	_	ns		
				PIC16LC62/64	20	_	_	ns	
52*	TccP	CCP1 input period			<u>3Tcy + 40</u> N	—	_	ns	N = prescale value (1,4 or 16)
53	TccR	CCP1 output rise time	9	PIC16 C 62/64		10	25	ns	
				PIC16LC62/64	_	25	45	ns	
54	TccF	CCP1 output fall time		PIC16 C 62/64	-	10	25	ns	
				PIC16LC62/64	-	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

	Applicable Devices	61	62	62A	B62	63	B63	64	64A	R64	65	65A	B65	66	67
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		Standa	rd Operat	ina (Conditior	ns (unle	ess otherwise stated)			
			ng temper	•		•	TA \leq +125°C for extended,			
	ARACTERISTICS				-40°	C ≤	TA \leq +85°C for industrial and			
	ANACIENISTICS	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial								
				VDD	range as	descri	bed in DC spec Section 18.1 and			
		Section 18.2								
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions			
No.				†						
	Output High Voltage									
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C			
D090A			VDD-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°С to +125°С			
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С			
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°С to +125°С			
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin			
	Capacitive Loading Specs on Out-									
	put Pins									
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.			
D101	All I/O pins and OSC2 (in RC mode)	Cio	-	-	50	pF				
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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FIGURE 18-8: PARALLEL SLAVE PORT TIMING (PIC16C64A/R64)

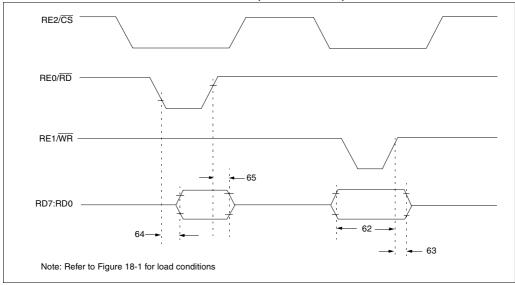


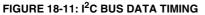
TABLE 18-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C64A/R64)

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time)		20	_	_	ns	
				25	_	-	ns	Extended Range Only
63*	TwrH2dtl	\overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data–in invalid (hold	PIC16 C 64A/R64	20	—	—	ns	
		time)	PIC16 LC 64A.R64	35	_	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		I	_	80	ns	
				—	_	90	ns	Extended Range Only
65*	TrdH2dtI	RD↑ or CS↑ to data–out invalid		10	_	30	ns	

These parameters are characterized but not tested.

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not t tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



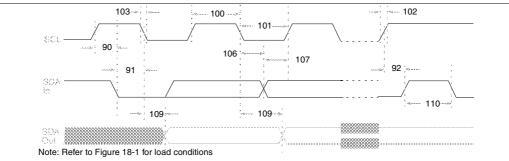


TABLE 18-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Тнідн	Clock high time	100 kHz mode	4.0	-	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise	100 kHz mode	—	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	_	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	—	μs	Only relevant for repeated
		setup time	400 kHz mode	0.6	—	μs	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0	—	μs	After this period the first clock
		time	400 kHz mode	0.6	_	μs	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0	_	ns	
			400 kHz mode	0	0.9	μs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6	—	μs	
109*	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3	_	μs	before a new transmission can start
	Cb	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

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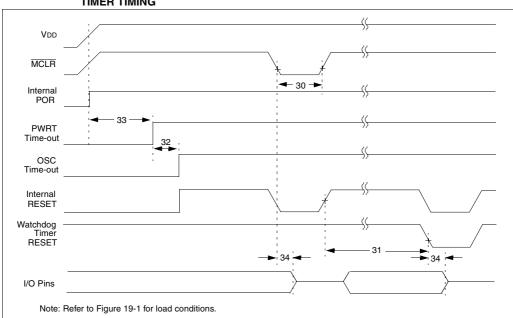


FIGURE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

TABLE 19-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30*	TmcL	MCLR Pulse Width (low)	100	—	—	ns	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	$VDD = 5V$, $-40^{\circ}C$ to $+85^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	_	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period or WDT reset	28	72	132	ms	$VDD = 5V, -40^{\circ}C \text{ to } +85^{\circ}C$
34	Tioz	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low	_	_	100	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



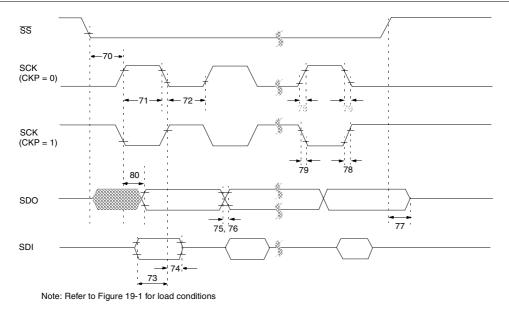


TABLE 19-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
70	TssL2scH, TssL2scL	\overline{SS} ↓ to SCK↓ or SCK↑ input	Тсү	—	—	ns	
71	TscH	SCK input high time (slave mode)	Tcy + 20	_	_	ns	
72	TscL	SCK input low time (slave mode)	Tcy + 20	_	_	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	_	—	ns	
75	TdoR	SDO data output rise time		10	25	ns	
76	TdoF	SDO data output fall time	-	10	25	ns	
77	TssH2doZ	SS↑ to SDO output hi-impedance	10	_	50	ns	
78	TscR	SCK output rise time (master mode)	_	10	25	ns	
79	TscF	SCK output fall time (master mode)	_	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	_	_	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

22.3 DC Characteristics: PIC16C66/67-04 (Commercial, Industrial, Extended) PIC16C66/67-10 (Commercial, Industrial, Extended) PIC16C66/67-20 (Commercial, Industrial, Extended) PIC16LC66/67-04 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated)									
		Operati	ng temper	ature			$A \le +125^{\circ}C$ for extended,				
DC CHA	ARACTERISTICS				-40°0		$A \le +85^{\circ}C$ for industrial and				
50 01.		_			0°C		$A \le +70^{\circ}C$ for commercial				
			ng voltage ction 22.2	VDD	range as	describ	bed in DC spec Section 22.1				
Davama		Conditions									
Param No.	Characteristic	Sym	Min	Тур †	Max	Units	Conditions				
	Input Low Voltage										
	I/O ports	VIL									
D030	with TTL buffer		Vss	-	0.15VDD	v	For entire VDD range				
D030A			Vss	-	0.8V	V	$4.5V \le VDD \le 5.5V$				
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	V					
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	V					
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	v	Note1				
	Input High Voltage										
	I/O ports	Vін		-							
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le V$ DD $\le 5.5V$				
D040A			0.25VDD	-	Vdd	V	For entire VDD range				
			+ 0.8V				Ũ				
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	V	For entire VDD range				
D042	MCLR		0.8VDD	-	Vdd	V					
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	Vdd	V	Note1				
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V					
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS				
	Input Leakage Current (Notes 2, 3)										
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \le VPIN \le VDD$, Pin at hi-				
							impedance				
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \leq V \text{PIN} \leq V \text{DD}$				
D063	OSC1		-	-	±5	μA	$Vss \leq VPIN \leq VDD, XT, HS and$				
							LP osc configuration				
	Output Low Voltage										
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5 V,				
							-40°C to +85°C				
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5 V,				
D 000							-40°C to +125°C				
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5 V,				
Dooot					0.0	N N	-40°C to +85°C				
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C				
			L				-40 0 10 +125 0				

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

*

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



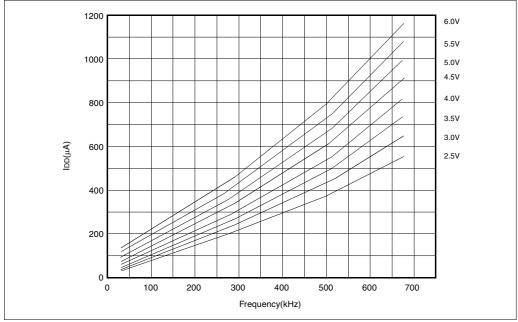
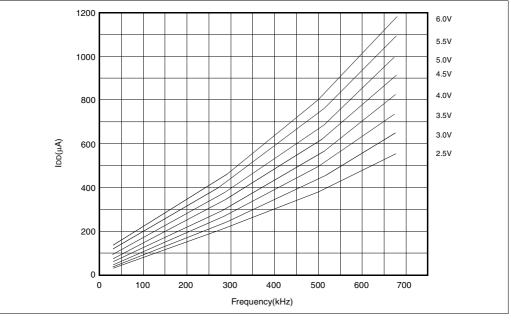


FIGURE 23-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

F.5 PIC16C55X Family of Devices

		PIC16C554	PIC16C556 ⁽¹⁾	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
lemory	Data Memory (bytes)	80	80	128
	Timer Module(s)	TMR0	TMR0	TMR0
Peripherals	Comparators(s)	—	—	—
	Internal Reference Voltage	—	—	—
	Interrupt Sources	3	3	3
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0
eatures	Brown-out Reset	—	—	—
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C5XX Family devices use serial programming with clock pin RB6 and data pin RB7. Note 1: Please contact your local Microchip sales office for availability of these devices.

F.6 PIC16C62X and PIC16C64X Family of Devices

		PIC16C620	PIC16C621	PIC16C622	PIC16C642	PIC16C662
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2К	4K	4K
	Data Memory (bytes) 80		80	128	176	176
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0
Peripherals	Comparators(s)	2	2	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes	Yes	Yes
	Interrupt Sources	4	4	4	4	5
	I/O Pins	13	13	13	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	3.0-6.0	3.0-6.0
	Brown-out Reset	Yes	Yes	Yes	Yes	Yes
Features	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin PDIP, SOIC, Windowed CDIP	40-pin PDIP, Windowed CDIP; 44-pin PLCC, MQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high

I/O current capability. All PIC16C62X and PIC16C64X Family devices use serial programming with clock pin RB6 and data pin RB7.